

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5756563

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16496928
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SIGNATURE:	/Julia Church Dierker, Reg. No. 33368/
DATE SIGNED:	10/07/2019

PATENT

Total Attachments: 2

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HP Inc.
3390 E. Harmony Road
Mail Stop 35
Fort Collins, Colorado 80528

PATENT APPLICATION

RECORD ID: 84601525

ASSIGNMENT OF PATENT APPLICATION

I/We, the undersigned (each), for good and valuable consideration, the receipt of which is hereby acknowledged, and in furtherance of my/our obligations to HEWLETT-PACKARD INDUSTRIAL PRINTING LTD., having its principal place of business in Netanya, Israel, (hereinafter HPIP), and to its subsidiaries and affiliates, in furtherance of my/our obligations to HPIP and its subsidiaries and affiliates, agree to assign and transfer and hereby assign and transfer to HPIP, its successors and assigns, the entire right, title and interest, including the right of priority, in, to and under an application for Patent entitled:

Piezo-jetable varnish composition

Filing Date: September 23, 2019

Application No.: 16/496,928

and the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part (C-I-P's), divisionals, and renewals of and substitutes for said application for said Patent, and any and all other Patent of any countries thereto which may be granted thereon or therefore; and any reissues, or reexaminations, or extensions of said Patent.

I/we additionally authorize HPIP to file applications in my/our name for Patent in any country, to be held and enjoyed by HPIP, its successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Patent respectively may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by me/us had this assignment, and transfer not been made;

AND I/we hereby covenant that I/we have full right to convey the entire interest herein assigned, and that I/we have not executed and will not execute any agreement in conflict herewith, and I/we further covenant and agree that I/we will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said invention(s) or improvement(s), said application and said Patent, to HPIP, its successors, assigns, nominees or legal representatives, and I/we agree to communicate to HPIP, or to its nominee, all known facts respecting said invention(s) or improvement(s), said application and said Patent, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisionals, continuations, C-I-P's, reissue and foreign applications, to make all rightful oaths and declarations, and generally to do everything possible to aid HPIP, its successors, assigns, nominees and legal representatives to obtain and enforce, for its or their own benefit, proper patent protection for said invention(s) or improvement(s) in any and all countries provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by HPIP;

AND I/we hereby authorize and request the official of any country or countries whose duty it is to issue patents on applications as aforesaid, to issue to HPIP, as assignee of the entire right, title and interest, any and all Patent for said invention(s) or improvement(s) which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of this assignment.

I/we further authorize and direct the attorneys of record to insert the filing date and application number of said application for Patent, now identified by the attorney docket number and title set forth above, as soon as the same shall have been made known to them.

IN WITNESS WHEREOF, I/we hereunto set my/our hand(s) and seal(s):

Inventor's Signature

Date

4/20/17

Eytan

Cohen

First/Middle Name

Last Name

Inventor's Signature

Date

4/20/17

Alex

Trubnikov

First/Middle Name

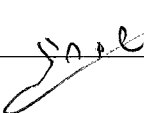
Last Name

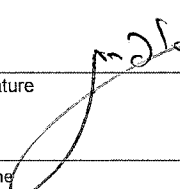
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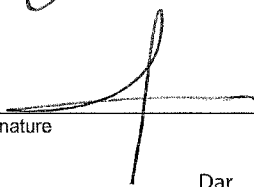
PATENT APPLICATION

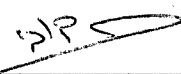
RECORD ID: 84601525

ASSIGNMENT OF PATENT APPLICATION (cont.)

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